



# BAP70-04W

Silicon PIN diode

Rev. 5 — 13 December 2018

Product data sheet

## 1 Product profile

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### 1.1 General description

Two planar PIN diodes in series configuration in an SOT323 small SMD plastic package.

### 1.2 Features and benefits

- High-voltage current control RF resistor for RF attenuators
- Low diode capacitance
- Low series inductance
- AEC-Q101 qualified

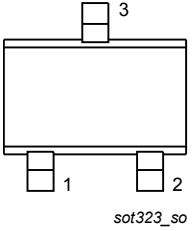
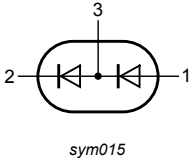
### 1.3 Applications

- RF attenuators and switches



## 2 Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	anode		
2	cathode		
3	common connection		

## 3 Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
BAP70-04W	-	plastic surface-mounted package; 3 leads	SOT323

## 4 Marking code

Table 3. Marking code

Type number	Marking code
BAP70-04W	1N%

## 5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	continuous reverse voltage		-	50	V
$I_F$	continuous forward current		-	100	mA
$P_{tot}$	total power dissipation	$T_{sp} \leq 90\text{ °C}$	-	260	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-65	+150	°C

## 6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-s)}$	thermal resistance from junction to solder point		230	K/W

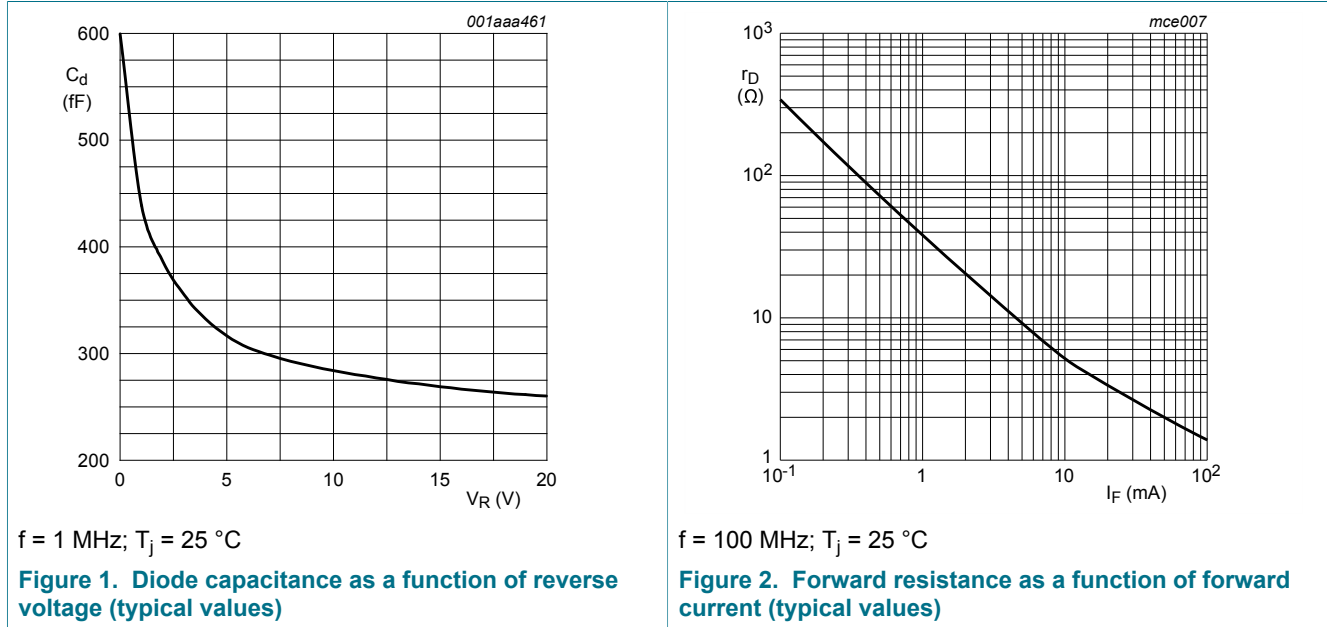
## 7 Characteristics

**Table 6. Characteristics**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
$I_R$	reverse current	$V_R = 50\text{ V}$	-	-	100	nA
$C_d$	diode capacitance	f = 1 MHz (see <a href="#">Figure 1</a> )				
		$V_R = 0\text{ V}$	-	600	-	fF
		$V_R = 1\text{ V}$	-	430	-	fF
		$V_R = 20\text{ V}$	-	250	300	fF
$r_D$	diode forward resistance	f = 100 MHz (see <a href="#">Figure 2</a> )				
		$I_F = 0.5\text{ mA}$	-	77	100	$\Omega$
		$I_F = 1\text{ mA}$	-	40	50	$\Omega$
		$I_F = 10\text{ mA}$	-	5.4	7	$\Omega$
$\tau_L$	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$ ; $R_L = 100\ \Omega$ ; measured at $I_R = 3\text{ mA}$				
		-	1.25	-	$\mu\text{s}$	
$L_S$	series inductance	$I_F = 100\text{ mA}$ ; f = 100 MHz	-	1.4	-	nH

**8 Graphical data**



**9 Package outline**

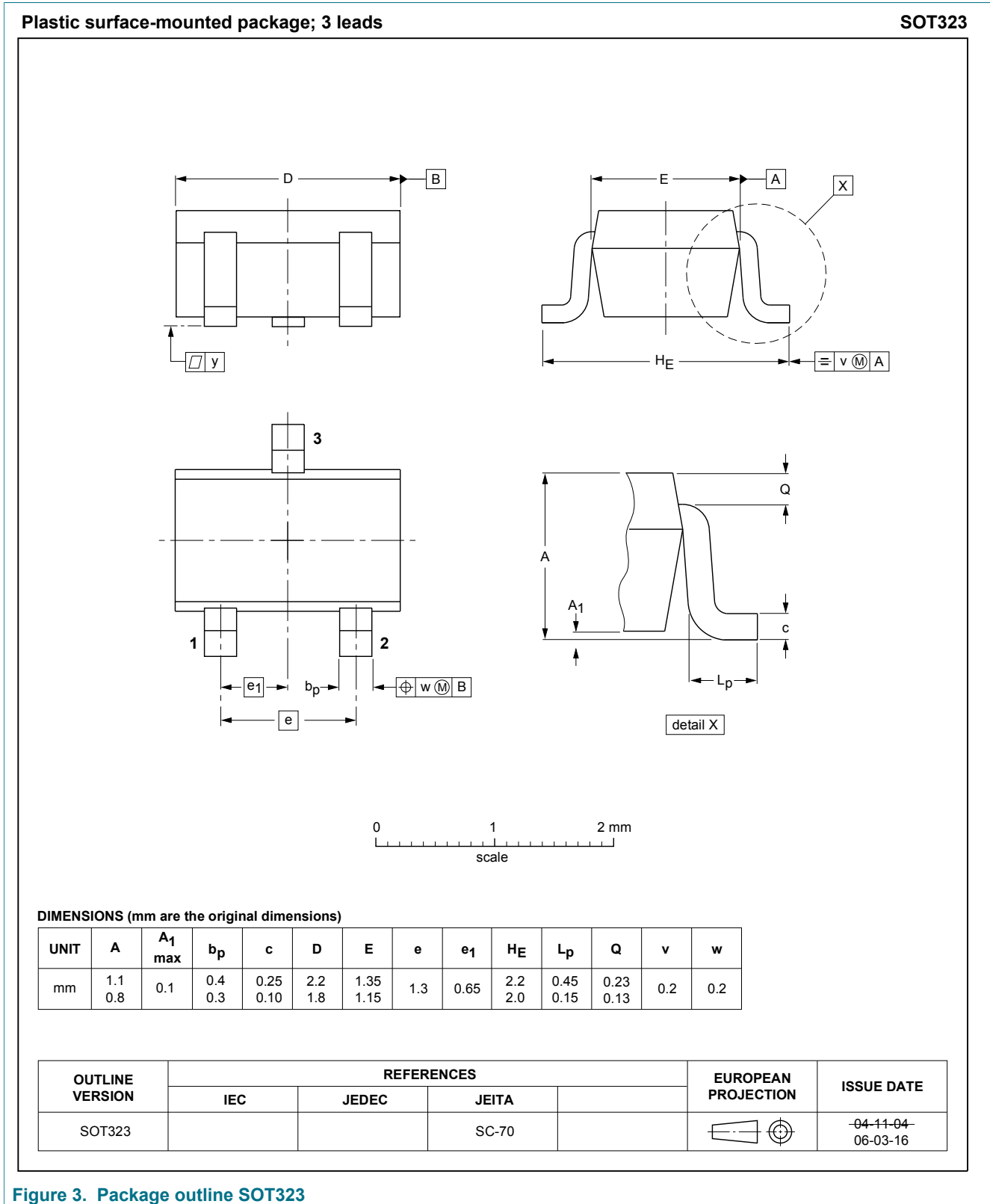


Figure 3. Package outline SOT323

## 10 Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP70-04W v.5	20181213	Product data sheet	-	BAP70-04W v.4
Modifications:	<ul style="list-style-type: none"><li>• <a href="#">Section 1.2</a> "Features and benefits" has been updated.</li><li>• adapted marking code</li><li>• The "Legal information" pages have been updated.</li></ul>			
BAP70-04W v.4	20140416	Product data sheet	-	BAP70-04W v.3
BAP70-04W v.3	20140128	Product data sheet	-	BAP70-04W v.2
BAP70-04W v.2	20070403	Product data sheet	-	BAP70-04W v.1
BAP70-04W v.1 (9397 750 12557)	20040305	Product data	-	-

## 11 Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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